

Title (en)

ABRADING DEVICE AND ABRADING METHOD EMPLOYING THE SAME

Title (de)

SCHLEIFVORRICHTUNG UND VERFAHREN ZUR VERWENDUNG DESSELBEN

Title (fr)

DISPOSITIF ABRASIF ET PROCEDE D'ABRASION UTILISANT CE DISPOSITIF

Publication

**EP 0607441 B1 19981209 (EN)**

Application

**EP 93904297 A 19930212**

Priority

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- JP 5929292 A 19920212
- JP 9300173 W 19930212

Abstract (en)

[origin: WO9315878A1] A device for abrading a large-scale flat substrate such as a silicon wafer, a quartz substrate, a glass substrate, and a metallic substrate. A sample (B) is abraded and worked by means of an abrading surface plate (1) while it is fixed by means of a vacuum chuck (4) on a sample holding table (3) with an abrasive (8) being supplied from an abrasive supplying nozzle (7). An elastic body (201) is secured to the underside of the abrading surface plate (1), and an abrasive cloth (2) is then secured to the underside of the elastic body. Since a hard type of abrasive cloth (2) is used, micro recessed and raised portions of the sample (B) can be worked to become smooth, and the elastic body (201) acts to realize uniform working.

IPC 1-7

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CPC (source: EP)

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Cited by

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